

1. DESCRIPTION

Bisphenol A type epoxy based vinylester resin with graphene materials. It is a premium resin with improved reactivity and purity. It provides excellent corrosion resistance to a wide range of organic and inorganic acids, alkalis, oxidizing agents and salts in solution, etc. It has very good mechanical properties in both tensile and bending, and can be used with glass and carbon fiber. It has high electrical conductivity since its resistivity is 100 Ω^*m .

2. PROPERTIES

- **Very low material resistivity approximately 100 Ω^*m as semiconductor.**
- **Excellent performance against resistance to chemical agents.**
- **Fully compatible with carbon and glass fiber.**
- **High mechanical properties.**

3. APPLICATIONS

- In applications where the material is required to have electrical conductivity.
- Good intercoat adhesion and very low linear and volumetric shrinkage.
- The percentage of mek peroxide should be between 1 % and 1.5 %, although it can be increased up to 2% to reduce the gel time.
- The application can be manual or by machine.
- It can be used in pultrusion processes.

4. TECHNICAL CHARACTERISTICS

Appearance	Dark liquid
Density	1,1
Gel time (25°C) ⁽¹⁾	8 - 10 min
Viscosity brookfield (H2V30 , 25°C)	1200 – 1400 cps
Resistivity	100 Ω^*m

(1) 100/6% CoOct. 0,3% / 1.2% PMEK

5. MECHANICAL CHARACTERISTICS

Flexural modulus	3912 MPa
Flexural strength	30.63 MPa
Maximum deflection dL	0.77 mm
Tensile modulus	3010 MPa
Tensile strength	25.7 MPa
Elongation at break	0.86 %

6. STORAGE AND PACKAGING

- The product should be **stored in a dry place** at a temperature not exceeding **25°C**.
- The expiry date is **6 months** under these conditions.
- Existing containers are **IBCs and barrel**.
- For other quantities: **contact us**.